

C0603X331K2RACTU

Aliases (C0603X331K2RAC7867)

SMD Comm X7R Flex, Ceramic, 330 pF, 10%, 200 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 0603



Click [here](#) for the 3D model.

Dimensions

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.58mm MIN
B	0.45mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	SMD Comm X7R Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	7.3 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	330 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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